Version 4.2

QILIUM MULTI-APPLICATIVE INTEGRATED CIRCUIT

MULTIQ_e secure people IDentity

Payment and e-service access in a single solution



Advanced access control



ICAO identification



payment





MNO SIM M2M eUICC

MULTIQ is a card operating system (COS) providing a large set of configurations in contact, contactless and dual interface. Complying with ISO/IEC 7816-3 and ISO/IEC 14443 A/B standards, MULTIQ allows to address multiple projects with a single micro-controller. Offering best-in-class technology in terms of data transfer rates (up to 848 Kbps), anti-tearing and transaction protection mechanism, MULTIQ characterises QILIUM state-of-the-art Integrated Circuit (IC) technology.

Embedded into smart card, ticket, label or object, MULTIQ let access to various configurations such as ICAO for Identity or EMV CPA for payment. Its 4-stages lifecycle and several configurations confers to MULTIQ a true flexibility permitting to manage a single chip environment while addressing different markets following diverse standards.

From Advanced Access Control systems verifying Biometrics (Finger prints, Iris or Face) with Match-on-Device to electronic voting systems requiring anonymous card authentication, MULTIQ provides an easyto-integrate ISO/IEC 7816-4 compliant solution. Featuring best-in-class security with secure messaging and mutual authentication, MULTIQ provides several possibilities in term of Data structure creation and Access conditions definition.

MAIN FEATURES

- Adaptable and flexible file structure
- File system based on ISO/IEC 7816-4
- > No restriction in the number of applications
- Delete of file without memory loss
- > Transport key protection
- ➢ Customizable ATR
- > Anti-tearing system
- Transaction protection system
- Detection of Fraudulent chips
- > Anti-collision
- Memory Sizes:

<u>Contact</u>: Up to 72 Kb EEPROM <u>Contactless</u>: Up to 160 kB EEPROM Dual Interface: Up to 160 kB EEPROM

SECTORS

- > GOVERNMENT
 - E-ID | E-Passport | E-Driving Licence

OFF ON

Gilium

n))

- o E-Health
- > ENTERPRISE SECURITY
 - o Physical & Logical Access Control
- ➢ PUBLIC TRANSPORTATION
 - o Ticketing
- BANKING & PAYMENT
 - o Debit/Credit
 - o Pre-/-Post Paid
 - o Close-loop money
- > MARKETING
 - o Gift | Loyalty | Member card
- > TELECOMMUNICATION

All rights reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.



©2018 Qilium S.A.

SECURITY

PIN CODE

- o at card level
- o at application Level
- ➢ KEY FILE
 - o at card level
 - o at application Level
- SECURE MESSAGING
 - o MAC
 - O MAC + ENC
 - MSE (Manage security environment)

CRYPTOGRAPHIC ALGORITHMS

- > DES/3DES
- > AES (up to 256-bit)*
- ➢ SHA 1 & 2
- RSA (up to 4096-bit)*
- ➢ ECC (up to 521-bit)*

* Depends on semiconductor and its cryptographic library.

COMMUNICATION PROTOCOLS

Contact

- ISO/IEC 7816-3 | T=0 / T=1
- High speed data transfer up to 215 Kbits/s

Contactless

- ISO/IEC 14443 | A/B
- High speed data transfer up to 848 Kbits/s

Dual interface

- ➢ ISO/IEC 7816-3 | T=0 / T=1
- ISO/IEC 14443 | A / B

CONFIGURATIONS

- > MULTIQ
- ICAO / MRTD
- NFC
- ➤ CIPURSE[™] **
- ➤ EMV**
- ➤ SAM**

ICAO DOC 9303 NDEF | SECURE NDEF OSPT | CIPURSE™ EMV 4.2 | CPA | SDA

ISO/IEC 7816-4

 $\ast\ast$ Withthis configuration solely ISO/IEC 7816-4 File Structure can be added.

PACKAGING

Sawn wafer

0

Contact module

o 8 pins

6 pins

- Contactless modulePrelaminates
 - o PVC
 - Polycarbonate

Inductive technology

- o Infineon
- o SPS

TECHNOLOGY

Packaging	Contact	Contactless	Dual Interface
Standard	Up to 72 kB	Up to 74 kB	Up to 74 kB
Certified***	-	Up to 160 kB	Up to 160 kB
Advanced cryptography	-	Up to 100 kB	Up to 100 kB

*** Common Criteria EAL5+ high HW

©2017 Oilium S.A.

cument does not form part of any of its use. Publication thereof does